AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions of claims in the application.

Listing of Claims:

Claims 1-18: (Cancelled).

Claim 19 (Previously Presented): A tool for mounting or removing an electrical component mounted on a printed circuit card having connection pads on opposite sides and a plurality of through holes for receiving mounting means therein for mounting the electrical components on opposite sides of the card, comprising means for exerting pressure on a first electrical component mounted on a first side of the printed circuit card, in order to mount or remove a second electrical component on the opposite side of the printed circuit card (2).

Claim 20 (Previously Presented): A tool (35) according to claim 19, wherein means for exerting pressure comprise springs having axes that coincide with the axis of the mounting means.

Claim 21 (Previously Presented): A tool according to claim 20 wherein the mounting means comprise a plurality of stand offs arranged to exert a substantially equal pressure force on each side of the printed circuit card to maintain contact between the first and second electrical components and the connecting pads.

Claim 22 (Previously Presented): A tool for mounting or removing an electrical component from a printed circuit card, and comprising mounting means, at least two electrical components on the printed circuit card, the card having connection pads on opposite sides, said card being traversed by through holes for receiving said mounting means which are disposed to extend through the through holes of the

printed circuit card in order to mount the electrical components on opposite sides of the card, comprising means for exerting pressure on a first electrical component attached to a first side of the printed circuit card, in order to mount or remove a second electrical component on the opposite side of the printed circuit card (2).

Claim 23 (Previously Presented): A tool according to claim 22, wherein the mounting means exert equal pressure on each side of the printed circuit card (2), the mounting means comprising standoffs, each standoff comprising on both of its ends a threaded part capable of receiving a screw for attaching the integrated circuits.

Claim 24 (Previously Presented): A tool according to claim 23, further including a plate (8) on each side of the printed circuit card, said plate (8) including notches traversed by the standoffs, the shape of the holes and the standoffs preventing any rotational movement of the standoffs for mounting and removal.

Claim 25 (Previously Presented): A method of mounting electrical component assemblies on opposite sides of a printed circuit card, said printed circuit being provided with a plurality of through holes and having connection pads on a both sides, comprising:

inserting a chock on a first side of the card, said chock having a thickness about equal to a thickness of an electrical component assembly;

inserting a standoff through each through hole and placing a spring around each standoff;

pressing the chock against the printed circuit card;

mounting a first electrical component assembly on a second side of the printed

circuit card;

placing a package tool on a horizontal support, wherein said package tool comprises a plurality of springs, and placing the first mounted electrical component assembly inside the package tool, so that springs of the package tool come into contact with the first electrical component assembly;

removing the chock such that springs of the package exert a force that compensates for the weight of the first electrical component assembly inside the package; and

mounting a second electrical component assembly on a second side of the printed circuit card.

Claim 26 (Previously Presented): The method of claim 25, wherein the first and second electrical component assemblies are integrated circuits.

Claim 27 (Previously Presented): The method of claim 25, wherein said chock is pressed against the printed circuit card through screws in the standoffs.

Claim 28 (Previously Presented): The method of claim 25, wherein the step of mounting a first electrical component assembly comprises:

placing an insert having electrical contacts on the printed circuit card so that electrical contacts of the insert coincide with electrical contacts of the circuit card;

placing an electrical component having pins on the insert so the pins of the component coincide with electrical contacts of the insert;

placing a plate on the electrical component and the insert;

placing a heat sink on the plate, electrical component and insert; and

exerting pressure on the heat sink, plate, electrical component and insert to mount the assembly comprising the heat sink, plate, electrical component and insert to the circuit card.

Claim 29 (Previously Presented): A method of removing a mounted electrical component assembly from a printed circuit card, said printed circuit card having an electrical component assembly mounted on each side, and having standoffs inserted through through holes in the circuit card, comprising:

placing a first mounted electrical component assembly inside a package tool, wherein said package tool comprises springs, such that the springs come in contact with screws of the first electrical component assembly;

unscrewing screws of the first electrical component assembly, such that springs of the package tool exert a force compensating for the weight of the first electrical component assembly inside the package tool, and preventing movement of the package tool and first electrical component assembly from moving in a direction perpendicular to the standoffs; and

removing the first electrical component assembly.